

# CD4011A, CD4012A, CD4023A Types

## CMOS NAND Gates

Quad 2 Input – CD4011A

Dual 4 Input – CD4012A

Triple 3 Input – CD4023A

The TI-CD4011A, CD4012A, and CD-4023A NAND gates provide the system designer with direct implementation of the NAND function and supplement the existing family of CMOS gates.

These types are supplied in 14-lead hermetic dual-in-line ceramic packages (D and F suffixes), 14-lead dual-in-line plastic packages (E suffix), 14-lead ceramic flat packages (K suffix), and in chip form (H suffix).

### MAXIMUM RATINGS, Absolute-Maximum Values:

STORAGE-TEMPERATURE RANGE ( $T_{stg}$ ) . . . . . -65 to +150°C

OPERATING-TEMPERATURE RANGE ( $T_A$ ):

PACKAGE TYPES D, F, K, H . . . . . -55 to +125°C

PACKAGE TYPE E . . . . . -40 to +85°C

DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ ):

(Voltages referenced to  $V_{SS}$  Terminal) . . . . . -0.5 to +15 V

POWER DISSIPATION PER PACKAGE ( $P_D$ ):

FOR  $T_A = -40$  to +60°C (PACKAGE TYPE E) . . . . . 500 mW

FOR  $T_A = +60$  to +85°C (PACKAGE TYPE E) . . . . . Derate Linearly at 12 mW/°C to 200 mW

FOR  $T_A = -55$  to +100°C (PACKAGE TYPES D, F, K) . . . . . 500 mW

FOR  $T_A = +100$  to +125°C (PACKAGE TYPES D, F, K) . . . . . Derate Linearly at 12 mW/°C to 200 mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR  $T_A =$  FULL PACKAGE-TEMPERATURE RANGE (ALL PACKAGE TYPES) . . . . . 100 mW

INPUT VOLTAGE RANGE, ALL INPUTS . . . . . -0.5 to  $V_{DD}$  +0.5 V

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 ± 1/32 inch (1.59 ± 0.79 mm) from case for 10 s max . . . . . +265°C

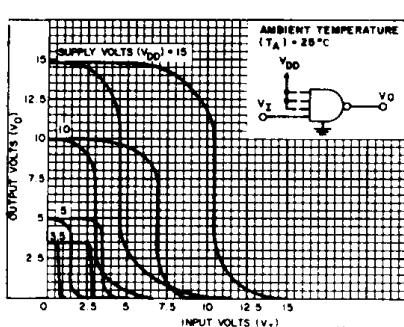


Fig. 2 – Minimum & maximum voltage transfer characteristics.

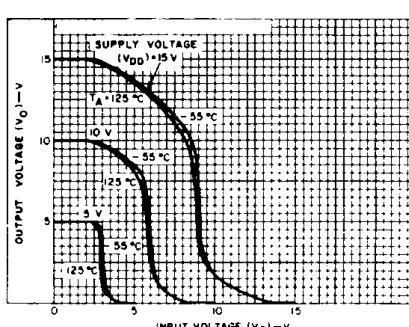


Fig. 3 – Typical voltage transfer characteristics as a function of temperature.

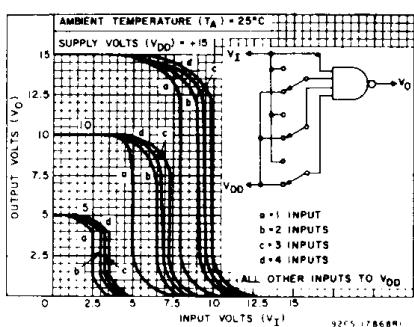


Fig. 4 – Typical multiple input switching transfer characteristics for CD4012A.

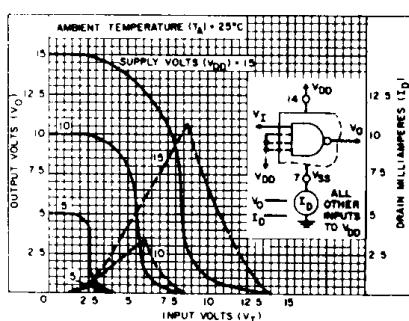
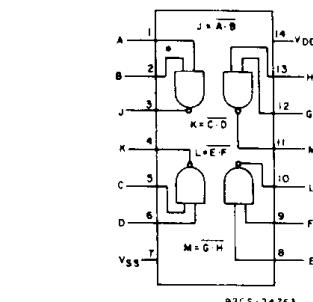
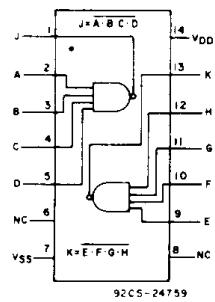


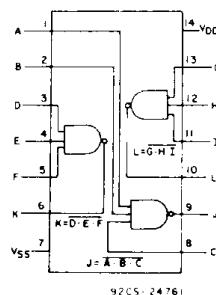
Fig. 5 – Typical current & voltage transfer characteristics.



CD4011A

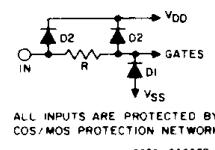


CD4012A



CD4023AH

Fig. 1 – Functional diagrams.



ALL INPUTS ARE PROTECTED BY  
COS/MOS PROTECTION NETWORK

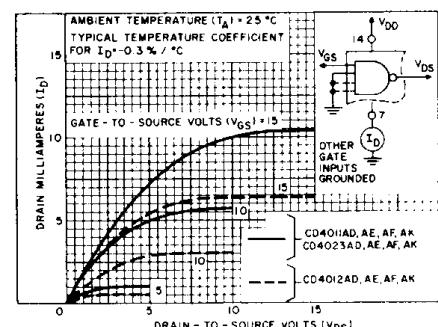


Fig. 6 – Typical n-channel drain characteristics.

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## STATIC ELECTRICAL CHARACTERISTICS

Characteristic	Conditions			Limits at Indicated Temperatures (°C)						Units	
	VO (V)	VIN (V)	VDD (V)	D,F,K,H Packages		E Package					
				-55	+25	+125	-40	+25	+85		
Quiescent Device Current, $I_L$ Max.	-	-	5	0.05	0.001	0.05	3	0.5	0.005	0.5	15 $\mu\text{A}$
	-	-	10	0.1	0.001	0.1	6	5	0.005	5	30
	-	-	15	2	0.02	2	40	50	0.5	50	500
Output Voltage: Low-Level VOL	-	0.5	5	0 Typ.; 0.05 Max.						V	
	-	0.10	10	0 Typ.; 0.05 Max.							
High Level, VOH	-	0.5	5	4.95 Min.; 5 Typ.						V	
	-	0.10	10	9.95 Min.; 10 Typ.							
Noise Immunity: Inputs Low, VNL	3.6	-	5	1.5 Min.; 2.25 Typ.						V	
	7.2	-	10	3 Min.; 4.5 Typ.							
Inputs High, VNH	1.4	-	5	1.5 Min.; 2.25 Typ.						V	
	2.8	-	10	3 Min.; 4.5 Typ.							
Noise Margin: Inputs Low, VNML	4.5	-	5	1 Min.						V	
	9	-	10	1 Min.							
Inputs High, VNMH	0.5	-	5	1 Min.						V	
	1	-	10	1 Min.							
Output Drive Current: N-Channel (Sink) $I_D$ Min. CD4011A										mA	
	0.5	-	5	0.31	0.5	0.25	0.175	0.145	0.5		
	0.5	-	10	0.62	0.6	0.5	0.35	0.3	0.6		
	0.5	-	CD4023A	0.31	0.15	0.25	0.12	0.085	0.072		
CD4012A	0.5	-	5	0.31	0.15	0.25	0.12	0.085	0.072	0.25	0.05 $\text{mA}$
	0.5	-	10	0.62	0.31	0.6	0.25	0.175	0.155	0.6	0.13 0.105 $\text{mA}$
P-Channel (Source), $I_D$ Min. All Types	4.5	-	5	-0.31	-0.5	-0.25	-0.175	-0.145	-0.5	-0.12 -0.095 $\text{mA}$	
	9.5	-	10	-0.75	-1.2	-0.6	-0.4	-0.35	-1.2	-0.3 -0.24 $\text{mA}$	
Input Leakage Current, $I_{IL}, I_{IH}$	Any Input	15	$\pm 10^{-5}$ Typ.; $\pm 1$ Max.							$\mu\text{A}$	

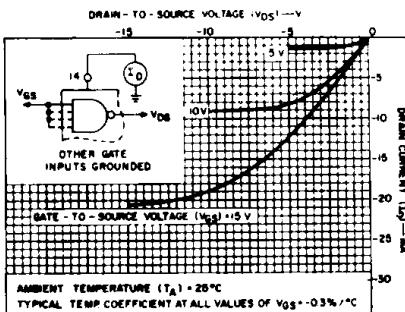


Fig. 7 — Typical p-channel drain characteristics.

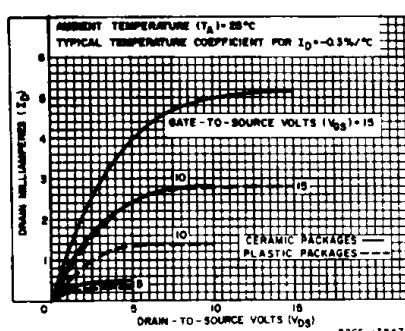


Fig. 8 — Minimum n-channel drain characteristics —CD4011A & CD4023A.

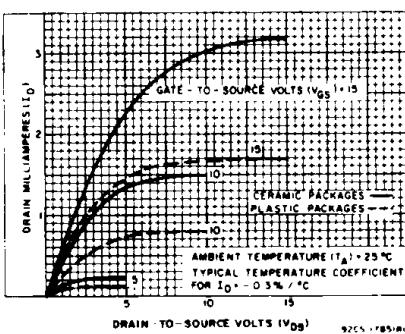


Fig. 9 — Minimum n-channel drain characteristics.

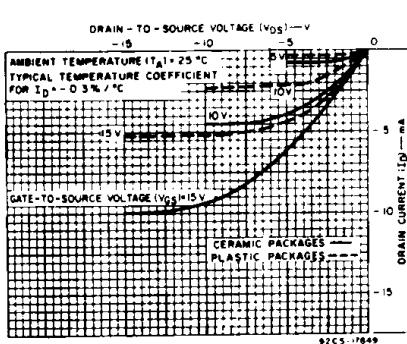


Fig. 10 — Minimum p-channel drain characteristics.

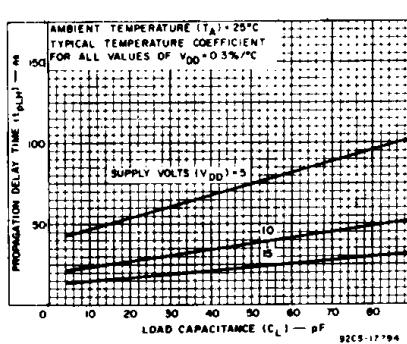


Fig. 11 — Typical low-to-high level propagation delay time vs.  $C_L$ .

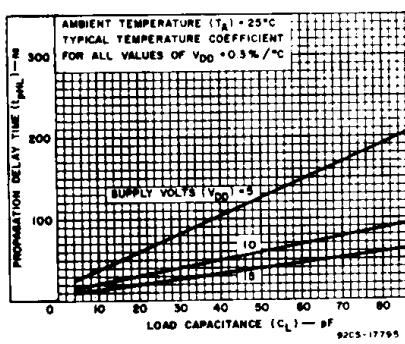


Fig. 12 — Typical high-to-low level propagation delay time vs.  $C_L$  — CD4011A, & CD4023A.

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DYNAMIC ELECTRICAL CHARACTERISTICS at  $T_A = 25^\circ\text{C}$ ,  $C_L = 15 \text{ pF}$ , Input  $t_r, t_f = 20 \text{ ns}$ ,  $R_L = 200 \text{ k}\Omega$

CHARACTERISTICS	TEST CONDITIONS	LIMITS				UNITS	
		D, F, K, H Packages		E Package			
		V <sub>DD</sub> (V)	Typ.	Max.	Typ.	Max.	
Propagation Delay Time: Low-to-High Level, $t_{PLH}$		5	50	75	50	100	ns
		10	25	40	25	50	
High-to-Low Level, $t_{PHL}$ CD4011A and CD4023A		5	50	75	50	100	ns
		10	25	40	25	50	
CD4012A		5	100	150	100	200	ns
		10	50	75	50	100	
Transition Time: Low-to-High Level, $t_{TLH}$		5	75	100	75	125	ns
		10	40	60	40	75	
High-to-Low Level, $t_{THL}$ CD4011A and CD4023A		5	75	125	75	150	ns
		10	50	75	50	100	
CD4012A		5	250	375	250	500	ns
		10	125	200	125	250	
Input Capacitance, $C_I$	Any Input	5	—	5	—	pF	

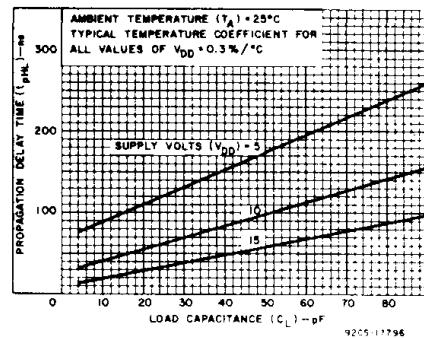


Fig. 13 — Typical high-to-low level propagation delay time vs.  $C_L$  — CD4012A.

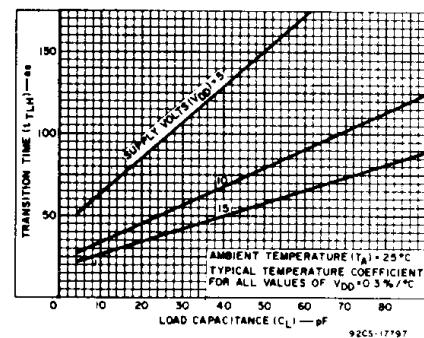


Fig. 14 — Typical low-to-high transition time vs.  $C_L$ .

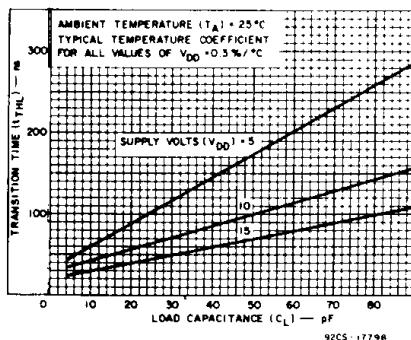


Fig. 15 — Typical high-to-low level transition time vs.  $C_L$  — CD4011A & CD4023A.

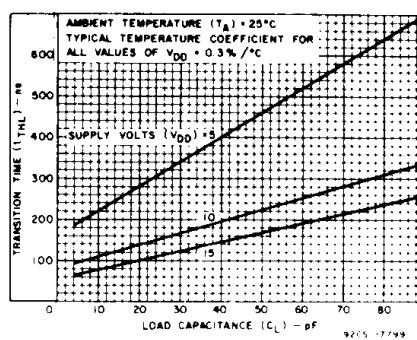


Fig. 16 — Typical high-to-low level transition time vs.  $C_L$  — CD4012A.

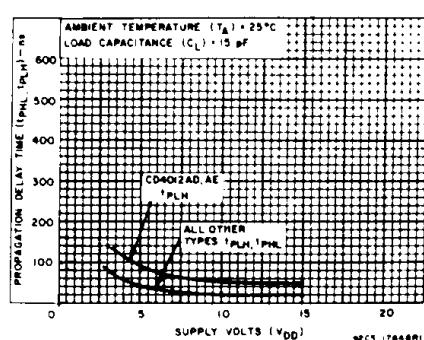


Fig. 17 — Minimum propagation delay time vs.  $V_{DD}$ .

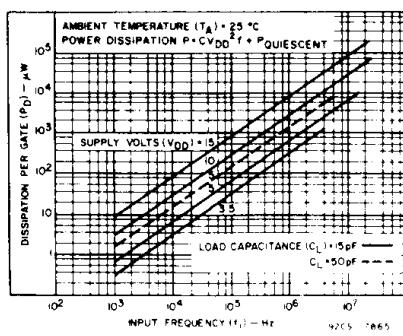


Fig. 18 — Typical dissipation characteristics.

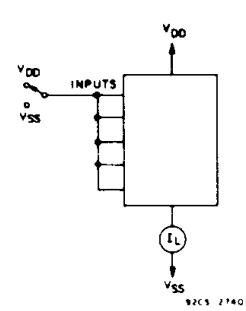


Fig. 19 — Quiescent device current test circuit.

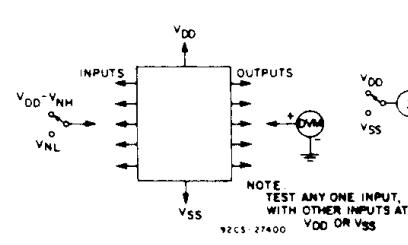


Fig. 20 — Noise immunity test circuit.

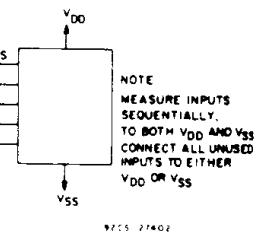


Fig. 21 — Input leakage current test circuit.

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